

Tyrone Camarero Specifications

Tyrone

Camarero: SDI200A3H-460

Key Feature

- Support HBM and CXL
- 5th/4th Gen Intel® Xeon® Scalable processors and Intel® Xeon® Max series processors, Dual Socket LGA-4677 (Socket E) supported, CPU TDP supports Up to 350W TDP,
- Intel C741® Chipset
- Up to 8TB 3DS ECC RDIMM, DDR5-5600MT/s in 32 DIMM slots
- 4 PCIe 5.0 x16 (in x16 slot), 2 PCIe 5.0 x16 AIOM Slot, AIOM slots Superset of OCP 3.0 Expansion
- **M.2 Interface:** 2 PCIe 3.0 x2
- 2 AIOM OCP 3.0 superset
- 8 NVMe ports PCIe 5.0 x8 via 8 MCIO connectors
- 2 M.2
- 1 VGA
- 2 USB 2.0 and 2 USB 3.0
- 60 x 2.5"/3.5" Top loading Bays (SAS/SATA) with 2 x 30 drive expander backplane
- 12 x 2.5"/3.5" Rear Bays (SAS/SATA/NVMe) with direct attached backplane
- 2000W(80 Plus Titanium Redundant PSUs)



Processor/Cache		Drive bays	
Processor	5th/4th Gen Intel® Xeon® Scalable processors and Intel® Xeon® Max series processors, Dual Socket LGA-4677 (Socket E) supported, CPU TDP supports Up to 350W TDP.	HDD Bays	60 x 2.5"/3.5" Top loading Bays (SAS/SATA) with 2 x 30 drive expander backplane 12 x 2.5"/3.5" Rear Bays (SAS/SATA/NVMe) with direct attached backplane
Chipset		Power Supply	
Chipset	Intel C741® Chipset	Power Supply	2000W(80 Plus Titanium Redundant PSUs)
System Memory		Cooling System	
Memory Capacity	Up to 8TB 3DS ECC RDIMM, DDR5-5600MT/s in 32 DIMM slots	1 AOC cooling Fan(s) (optional) 5 counter-rotation PWM 40x40x56mm Fan(s)	
Expansion Slot		Form Factor	
PCI-Express	4 PCIe 5.0 x16 (in x16 slot), 2 PCIe 5.0 x16 AIOM Slot, AIOM slots Superset of OCP 3.0 Expansion M.2 : M.2 Interface: 2 PCIe 3.0 x2	Form Factor	4U Rackmount
Integrated Onboard		Dimensions	
SATA	Intel® C741 controller for 8 SATA3 ports	Dimensions	1046.4*446.2*175.7 (D x W x H) 1191.5*446.2*175.7 (D x W x H) (with CMA)
Add-on Options		Email : Info@tyronesystems.com For more/current product information, Visit www.tyronesystems.com	
Raid Card	Optional		
Optical Drive	None		